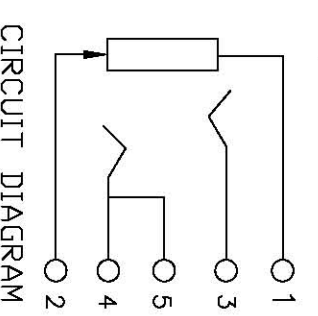
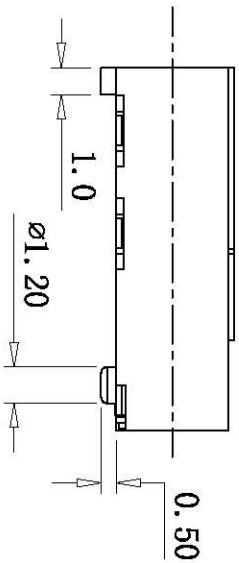
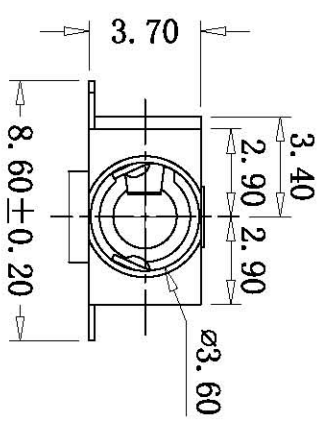
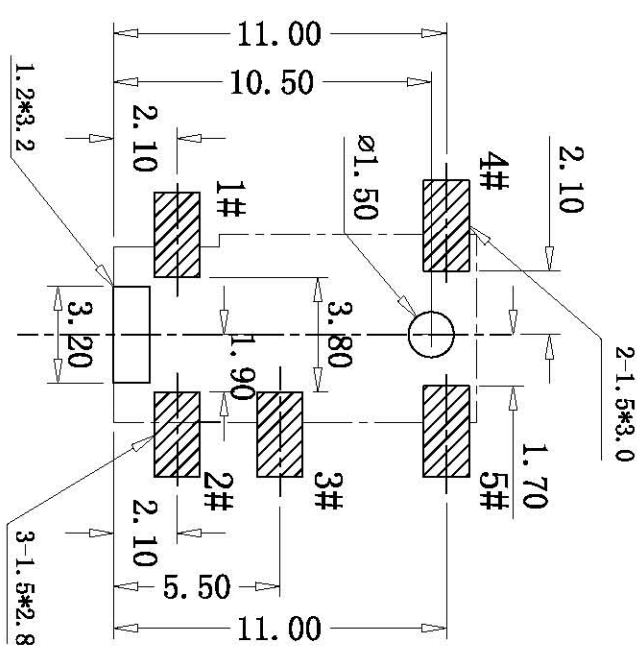
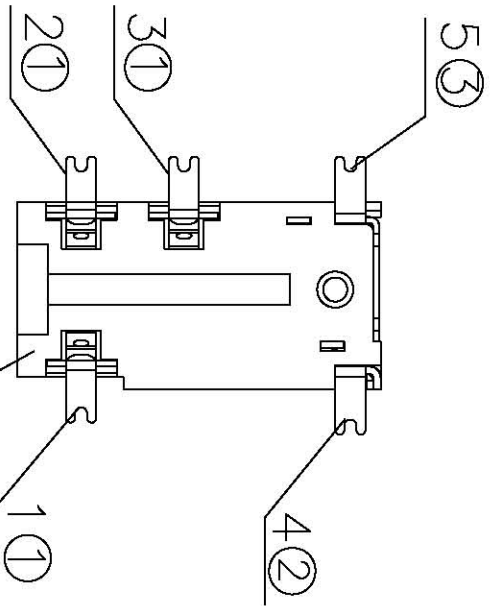
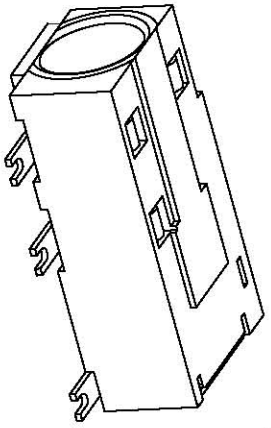
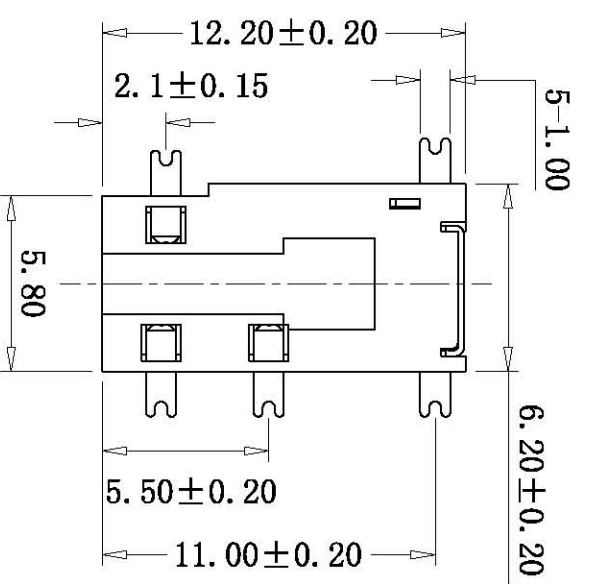


REV. ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A0		RELEASE TO CUSTOMER	080505	HANG
B				



CIRCUIT DIAGRAM



PCB LAYOUT TOP VIEW

No.	PART	QTY	MATERIAL	REMARK
④	HOUSING	1	PA9T (Black)	
③	TERMINAL	1	BRASS t=0.25	Ag-Plated
②	TERMINAL	1	PHOSPHOR BRONZE t=0.25	Ag-Plated
①	TERMINAL	3	PHOSPHOR BRONZE t=0.20	Ag-Plated

DIM	TOL	DIM	TOL
X.	±0.30	X'	±4.0'
XX	±0.25	XX'	±3.0'
XXX	±0.20	XXX'	±2.0'
XXXX	±0.10	XXXX'	±1.0'

DRAW NO.	09332-B05	DATE	090505
DESIGN	HANG	CHECK	WANGCM
APPROVED	HUYX	090506	
DRAW NAME:	Phone Jack SMT 无头		
P/N NO.	PJ-09332-B05-0N		
UNIT:	mm	SHEET:	N/A
MODEL:		REV. B	SCALE N/A

LASTAR
Lastar Technology CO., LTD